## Application Data Sh et

#### **Application Information**

Application Type::

Regular

Subject Matter::

Title::

Utility None

CD-ROM or CD-R?

Semiconductor Package With Substrate

Coupled To A Peripheral Side Surface Of

A Semiconductor Die

Attorney Docket Number::

BK-00006

Request for Early Publication?:: Request for Non-Publication?::

No YES

Suggested Drawing Figure::

1A

**Total Drawing Sheets::** 

14

Small Entity:: Petition included?:: No No

Secrecy Order in Parent Appl.?:: No

### **Applicant Information**

Applicant Authority type::

Inventor

Primary Citizenship Country::

Republic of Korea

Status::

**Full Capacity** 

Given Name::

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Middle Name::

Heo

Ш

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#### **Representative Information**

Representative Customer Number:: 022888

# **Assignee Information**

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